

Physical Security Attacks Against Silicon Devices



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CVEID: None

Summary

Texas Instruments has observed the increasing reports of physical security attacks against silicon devices, and recognizes this problem as an industry-wide issue. These types of attacks require physical access or close proximity to a potentially vulnerable device. Silicon devices (whether made by TI or another silicon vendor) designed without comprehensive mitigations against physical attacks, are potentially vulnerable. Fortunately, since an attacker must obtain physical access to the device, and may even need to make printed circuit board (PCB) modifications, these types of attacks do not, on their own, have the same potential for broad impact and scale as remote attacks. However, a physical attack may lead to information disclosures which may assist in the development of different remote attacks.

Physical attacks include, but are not limited to:

- Fault injection attacks, including voltage spike glitches, electromagnetic pulses, clock glitching injection, overclocking, and focused ion beam attacks
- Side-channel attacks against silicon, including power analysis and electromagnetic analysis

Common Vulnerability Scoring System (CVSS) base score: Can range from 4.8 to potentially as high as 6.1

The higher base score reflects a Confidentiality Impact of “High.” However, some systems may have a Confidentiality Impact of “Low” if the disclosure of the information programmed in the part does not represent a direct or serious loss. Additionally, the higher base score reflects an Attack Complexity of “Low.” However, some physical attacks (e.g., focused ion beam attacks) would be considered to have an Attack Complexity of “High.” In addition, physical controls preventing physical access to the part may raise the Attack Complexity metric for the overall system to “High.” Thus, several factors will impact the CVSS base score of a particular physical attack.

CVSS vector

- **High Score (6.1):** [CVSS:3.0/AV:P/AC:L/PR:N/UI:N/S:U/C:H/I:H/A:N](#)
- **Low Score (4.8):** [CVSS:3.0/AV:P/AC:H/PR:N/UI:N/S:U/C:L/I:H/A:N](#)

Affected products and versions

- If a TI product does not have documented mitigations against a specific physical attack, it may be vulnerable.
- If a TI product does have documented mitigations against a specific physical attack and a related vulnerability for that product is confirmed by TI, TI will publish a specific disclosure for that part.

Potentially impacted features

The following are generally known goals of physical attacks against silicon devices:

- Debug unlock,
- cryptographic key extraction, and
- general memory read-out.

Achievement of these goals may result in information disclosure of data stored on the device and may also result in the ability to program or reprogram the device.

Suggested mitigations

General techniques for mitigating physical attacks include the following:

- Physically secure the PCB in an enclosure using locks, security screws, potting, or other similar protections.
- Using sensors to detect the opening of the PCB's enclosure and deleting secrets when an unauthorized access is detected.
- Limiting impact of attack by using unique keys for each device and avoiding storing sensitive information in the device.

Texas Instruments is working to address the security needs of our customers as those needs evolve due to new attack methods. This pursuit includes investigating the addition of physical attack mitigations. If your company has questions about the availability of mitigations in TI parts, please reach out to your TI sales team.

Acknowledgment

We would like to thank researchers from COSIC, KU Leuven for reporting a specific instance of this potential vulnerability to the TI Product Security Incident Response Team (PSIRT).

Revision history

- Version 1.0 Initial publication

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